

Standard SMD LED PLCC-2



DESCRIPTION

This device has been designed to meet the increasing demand for AllnGaP technology.

The package of the TLMK310. is the PLCC-2 (equivalent to a size B tantalum capacitor).

It consists of a lead frame which is embedded in a white thermoplast. The reflector inside this package is filled up with clear epoxy.

PRODUCT GROUP AND PACKAGE DATA

Product group: LED
Package: SMD PLCC-2
Product series: standard
Angle of half intensity: ± 60°

FEATURES

SMD LED with exceptional brightness



- · Luminous intensity categorized
- Compatible with automatic placement equipment



- · EIA and ICE standard package
- Compatible with infrared, vapor phase and wave solder processes according to CECC
- Available in 8 mm tape
- · Low profile package
- Non-diffused lens: excellent for coupling to light pipes and backlighting
- Low power consumption
- Luminous intensity ratio in one packaging unit $I_{Vmax}/I_{Vmin} \le 1.6$
- · Lead (Pb)-free device

APPLICATIONS

- Automotive: backlighting in dashboards and switches
- Telecommunication: indicator and backlighting in telephone and fax
- Indicator and backlight for audio and video equipment
- · Indicator and backlight in office equipment
- · Flat backlight for LCDs, switches and symbols
- · General use

PARTS TABLE						
PART	COLOR, LUMINOUS INTENSITY	TECHNOLOGY				
TLMK3100-GS08	Red,I _V > 10 mcd	AllnGaP on GaAs				
TLMK3102-GS08	Red, I _V = (20 to 64) mcd	AllnGaP on GaAs				
TLMK3102-GS18	Red, I _V = (20 to 64) mcd	AllnGaP on GaAs				
TLMK3105-GS08	Red, I _V = (32 to 100) mcd	AllnGaP on GaAs				



ABSOLUTE MAXIMUM RATINGS ¹⁾ TLMK310.									
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT					
Reverse voltage		V _R	5	V					
DC Forward current	T _{amb} ≤ 60 °C	I _F	30	mA					
Surge forward current	t _p ≤ 10 μs	I _{FSM}	0.1	A					
Power dissipation	T _{amb} ≤ 60 °C	P _V	80	mW					
Junction temperature		T _j	100	°C					
Operating temperature range		T _{amb}	- 40 to + 100	°C					
Storage temperature range		T _{stg}	- 55 to + 100	°C					
Soldering temperature	t ≤ 5 s	T _{sd}	260	°C					
Thermal resistance junction/ ambient	mounted on PC board (pad size > 16 mm ²)	R _{thJA}	400	K/W					

Note:

 $^{^{1)}}$ T_{amb} = 25 $^{\circ}$ C, unless otherwise specified

OPTICAL AND ELECTRICAL CHARACTERISTICS ¹⁾ TLMK310., RED									
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN	TYP.	MAX	UNIT		
Luminous intensity ²⁾	I _F = 10 mA	TLMK3100	Ι _V	10	18		mcd		
		TLMK3102	Ι _V	20		63	mcd		
		TLMK3105	I _V	32		100	mcd		
Dominant wavelength	I _F = 10 mA		λ_{d}		630		nm		
Peak wavelength	I _F = 10 mA		λ_{p}		643		nm		
Angle of half intensity	I _F = 10 mA		φ		± 60		deg		
Forward voltage	I _F = 20 mA		V _F		1.9	2.6	V		
Reverse voltage	I _R = 10 μA		V_{R}	5			V		
Junction capacitance	V _R = 0, f = 1 MHz		C _j		15		pF		

Note:

TYPICAL CHARACTERISTICS

T_{amb} = 25 °C, unless otherwise specified

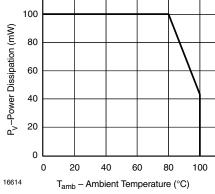


Figure 1. Power Dissipation vs. Ambient Temperature

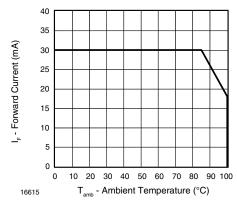


Figure 2. Forward Current vs. Ambient Temperature for InGaN

 $^{^{1)}}$ T_{amb} = 25 °C, unless otherwise specified

in one packing unit $I_{Vmax}/I_{Vmin} \le 2.0$





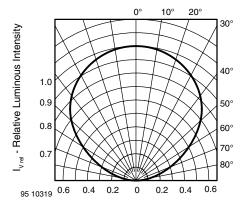


Figure 3. Rel. Luminous Intensity vs. Angular Displacement

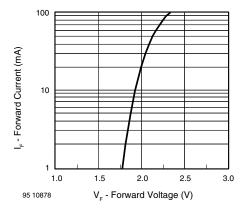


Figure 4. Forward Current vs. Forward Voltage

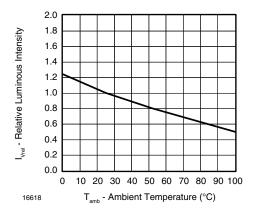


Figure 5. Rel. Luminous Intensity vs. Ambient Temperature

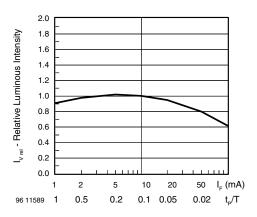


Figure 6. Rel. Lumin. Intensity vs. Forw. Current/Duty Cycle

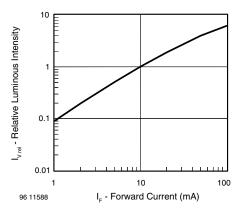


Figure 7. Relative Luminous Intensity vs. Forward Current

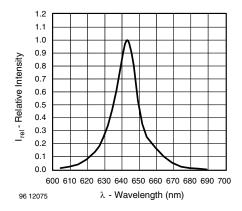


Figure 8. Relative Intensity vs. Wavelength



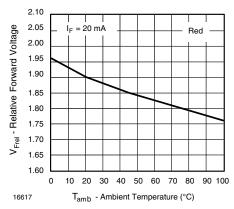


Figure 9. Forward Voltage vs. Ambient Temperature

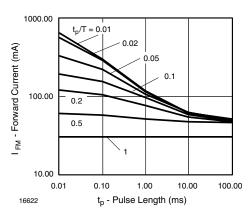
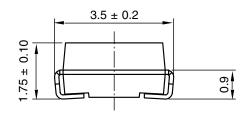
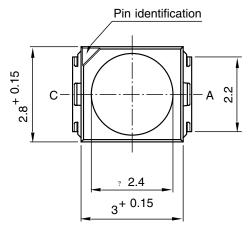


Figure 10. Forward Current vs. Pulse Length

PACKAGE DIMENSIONS in millimeters





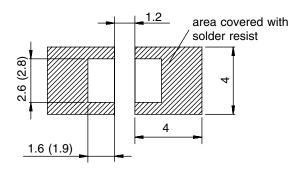


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Mounting Pad Layout





Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

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